ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES International and P	position De IPC, Bannockt an-American co	claration ourn, Illinois. A opyright conve	Il rights reserved untions.	nder both	This docume level parts, t	ent is a declaration he declaration er	on of the substan	ces within the ma wer level materia	nufacturer list lls for which t	ed item. Note: if he manufacturer	f the item is an as has engineering	ssembly with low responsibility.	
	IPC Web Site for Information on IPC-1752 Standard				/pe * Declaration Class * te Class 6 - RoHS Yes/No, Homogeneous Mate				s Materials an	rials and Mfg Information			
upplier Information													
Company name*			Company unique ID			Unique ID Authority				Response Date*			
onsemi						,				2024-05-18			
Contact Name Title - Con			- Contact			Phone - Contact*				Email - Contact*			
Product-Env-Stewards Proc			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Authorized Representative* Title - 1			tle - Representative			Phone - Representative*			Ema	Email - Representative*			
roduct-Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Requester Item Number	Mfr Item		Mfr Item Name			Effective Date	Version	Manufacturing Site		Weight*	UOM	Unit Type	
	MSRF86	ISRF860G 8A 600V SOFT		C TO-220FP		2024-05-18		KR8		2009.84	mg	Each	
Ianufacturing Proccess Inform	ation					•					·	·	
Terminal Plating / Grid Array M	Terminal Plating / Grid Array Material Terminal Base 2		Alloy	by J-STD-020 MSL Rating		Peak Process Body Temperature		ature Max Time	at Peak Temp	erature Numb	er of Reflow Cy	cles	
Matte Tin (Sn) - annealed		CU Alloy NA			0 C 3		30	se	econds 3				
omments													
or more information regarding materia	l composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chro	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DIBP).									
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such completes this form. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, itssuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier rinto a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or written agreement, the warranty rights and/or remedies of Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.											
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).								
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature	astislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	3.55	mg	Supplier	Silicon (Si)	7440-21-3		3.55	mg
Die Attach	82.98	mg	Supplier	Silver (Ag)	7440-22-4		1.2447	mg
			А	Lead (Pb)	7439-92-1	7a	77.5863	mg
			Supplier	Tin (Sn)	7440-31-5		4.149	mg
Lead Frame	1236.66	mg	Supplier	Copper (Cu)	7440-50-8		1236.66	mg
Mold Compound-Black	679.88	mg		Epoxy resin	proprietary data		47.5916	mg
			Supplier	Phenolic Resin	Proprietary Data		47.5916	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		101.982	mg
			Supplier	Carbon Black (C)	1333-86-4		3.3994	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		479.3154	mg
Plating	6.36	mg	Supplier	Tin (Sn)	7440-31-5		6.36	mg
Wire Bond - Al	0.41	mg	Supplier	Aluminum (Al)	7429-90-5		0.41	mg